

75A, 50V, 0.008 Ohm, N-Channel Power MOSFET

These are N-Channel enhancement mode silicon gate power field effect transistors. They are advanced power MOSFETs designed, tested, and guaranteed to withstand a specified level of energy in the breakdown avalanche mode of operation. All of these power MOSFETs are designed for applications such as switching regulators, switching convertors, motor drivers, relay drivers, and drivers for high power bipolar switching transistors requiring high speed and low gate drive power. These types can be operated directly from integrated circuits.

Formerly developmental type TA09821.

Ordering Information

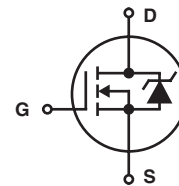
PART NUMBER	PACKAGE	BRAND
RFG75N05E	TO-247	RFG75N05E

NOTE: When ordering, include the entire part number.

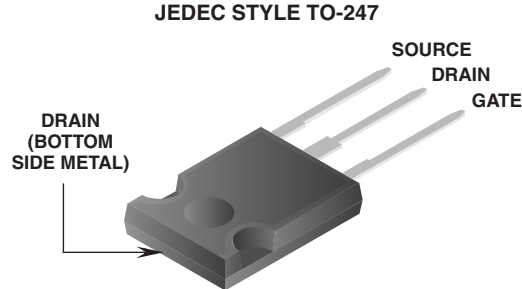
Features

- 75A, 50V
- $r_{DS(ON)} = 0.008\Omega$
- Electrostatic Discharge Rated
- UIS Rating Curve (Single Pulse)
- 175°C Operating Temperature
- Temperature Compensated PSPICE® Model Provided

Symbol



Packaging



RFG75N05E

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, Unless Otherwise Specified

	RFG75N05E	UNITS
Drain to Source Voltage (Note 1)	V_{DSS}	50 V
Drain to Gate Voltage ($R_{GS} = 20k\Omega$) (Note 1)	V_{DGR}	50 V
Continuous Drain Current (Current Limited by Package)	I_D	75 A
Pulsed Drain Current (Note 3)	I_{DM}	200 A
Gate to Source Voltage	V_{GS}	± 20 V
Maximum Power Dissipation	P_D	240 W
Linear Derating Factor		1.6 W/ $^\circ\text{C}$
Electrostatic Discharge Rating, MIL-STD-883, Category B(2)	E_{SD}	2 kV
Single Pulse Avalanche Rating (Note 4)	Refer to UIS SOA Curves	
Operating and Storage Temperature	T_J, T_{STG}	-55 to 175 $^\circ\text{C}$
Maximum Temperature for Soldering		
Leads at 0.063in (1.6mm) from Case for 10s	T_L	300 $^\circ\text{C}$
Package Body for 10s, See Techbrief 334	T_{pkg}	260 $^\circ\text{C}$

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

- $T_J = 25^\circ\text{C}$ to 125°C .

Electrical Specifications $T_C = 25^\circ\text{C}$, Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Drain to Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0V, I_D = 250\mu A$ (Figure 9)	50	-	-	V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu A$ (Figure 8)	2.0	-	4.0	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = \text{Rated } BV_{DSS}, V_{GS} = 0V$	-	-	1	μA
		$V_{DS} = 0.8 \times \text{Rated } BV_{DSS}, V_{GS} = 0V, T_C = 150^\circ\text{C}$	-	-	25	μA
Gate to Source Leakage	I_{GSS}	$V_{GS} = \pm 20V$	-	-	± 100	nA
Drain to Source on Resistance (Note 2)	$r_{DS(ON)}$	$V_{GS} = 10V, I_D = 75A$ (Figure 7)	-	-	0.008	Ω
Turn On Time	$t_{(ON)}$	$V_{DD} = 25V, I_D \approx 37.5A,$ $R_L = 0.67\Omega, R_G = 1.67\Omega, V_{GS} = 10V,$ (Figure 11)	-	-	125	ns
Turn On Delay Time	$t_{d(ON)}$		-	17	-	ns
Rise Time	t_r		-	75	-	ns
Turn Off Delay Time	$t_{d(OFF)}$		-	70	-	ns
Fall Time	t_f		-	17	-	ns
Turn Off Time	$t_{(OFF)}$		-	-	125	ns
Total Gate Charge (Gate to Source + Gate to Drain)	$Q_g(TOT)$	$V_{GS} = 0, 20V$	-	-	400	nC
Gate Charge at 10V	$Q_g(10)$	$V_{GS} = 0, 10V$				
Threshold Gate Charge	$Q_g(TH)$	$V_{GS} = 0, 2V$				
Junction to Case	$R_{\theta JC}$		-	-	0.625	$^\circ\text{C/W}$
Junction to Ambient	$R_{\theta JA}$		-	-	80	$^\circ\text{C/W}$

Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Source to Drain Diode Voltage	V_{SD}	$I_{SD} = 75A$	-	-	1.5	V
Diode Reverse Recovery Time	t_{rr}	$I_{SD} = 75A, dI_{SD}/dt = 100A/\mu s$	-	-	125	ns

NOTES:

- Pulse test: pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- Repetitive pulse: pulse width is limited by maximum junction temperature.
- Refer to Fairchild Application Notes AN9321 and AN9322. See Figure 4.

Typical Performance Curves Unless Otherwise Specified

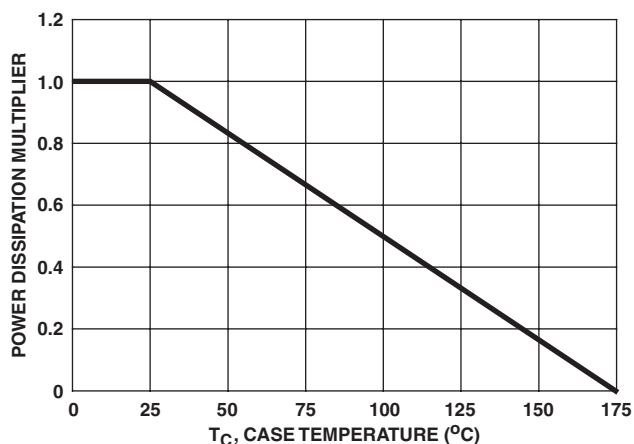


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

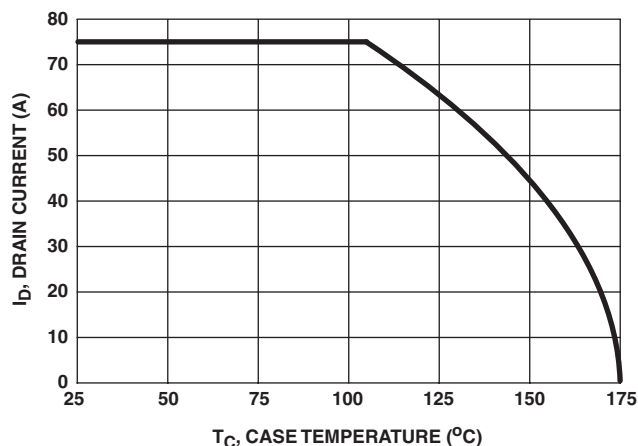


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

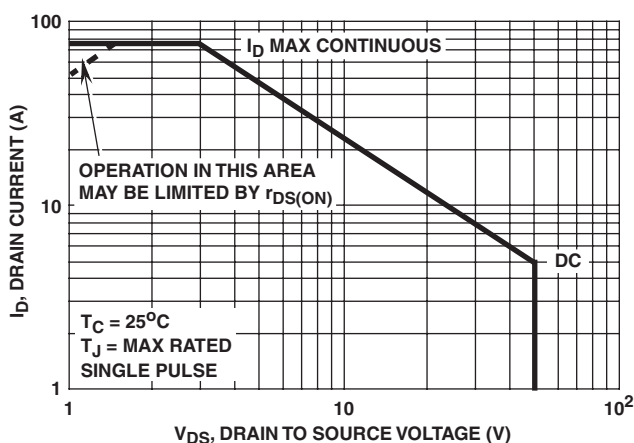


FIGURE 3. FORWARD BIAS SAFE OPERATING AREA

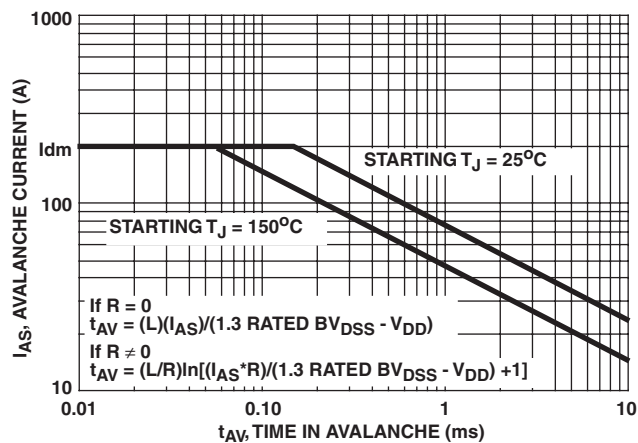


FIGURE 4. UNCLAMPED INDUCTIVE SWITCHING SOA (SINGLE PULSE UIS SOA)

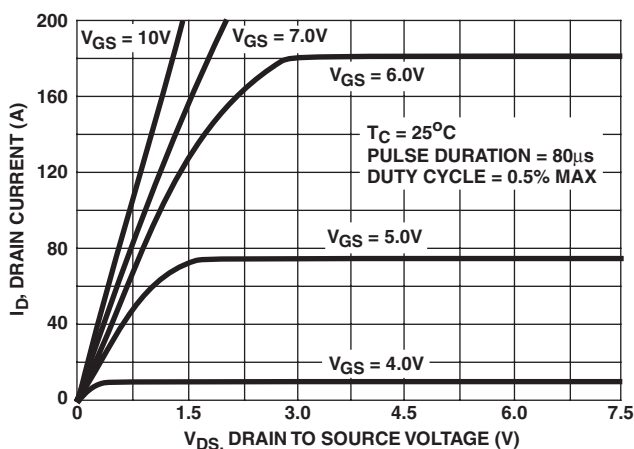


FIGURE 5. SATURATION CHARACTERISTICS

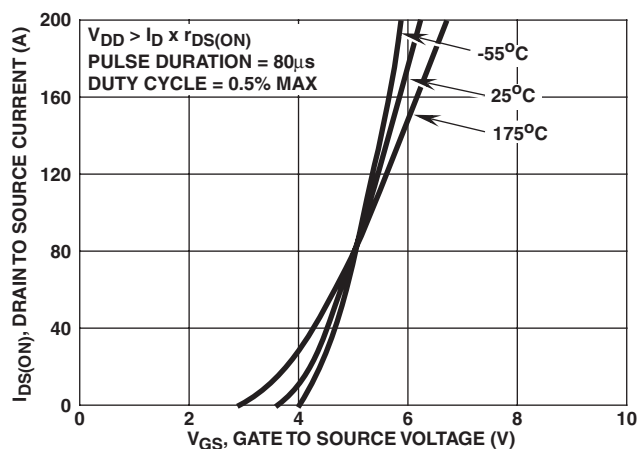


FIGURE 6. TRANSFER CHARACTERISTICS

Typical Performance Curves Unless Otherwise Specified (Continued)

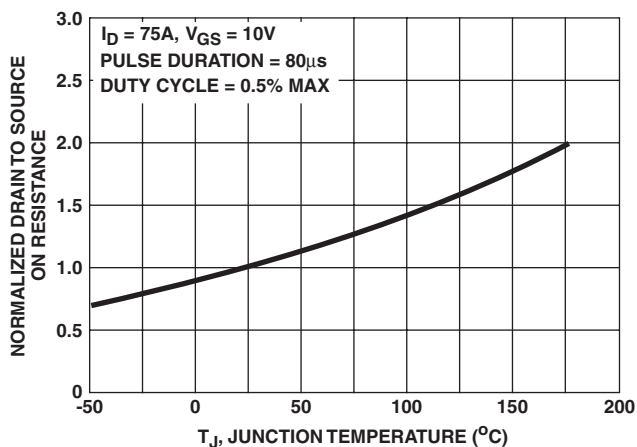


FIGURE 7. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE

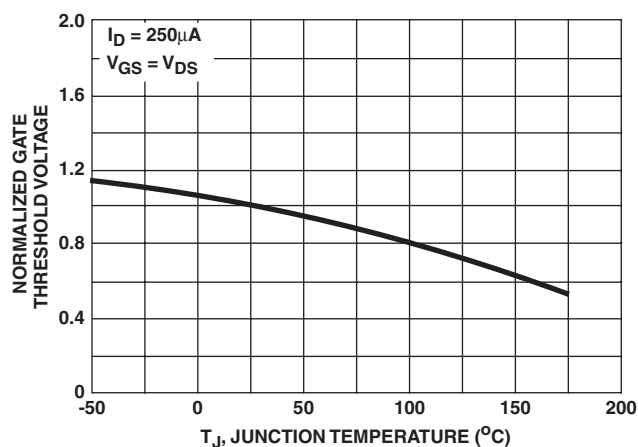


FIGURE 8. NORMALIZED GATE THRESHOLD VOLTAGE vs JUNCTION TEMPERATURE

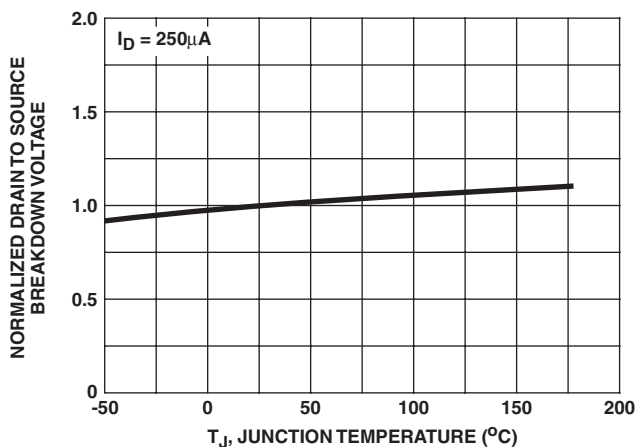


FIGURE 9. NORMALIZED DRAIN TO SOURCE BREAKDOWN VOLTAGE vs JUNCTION TEMPERATURE

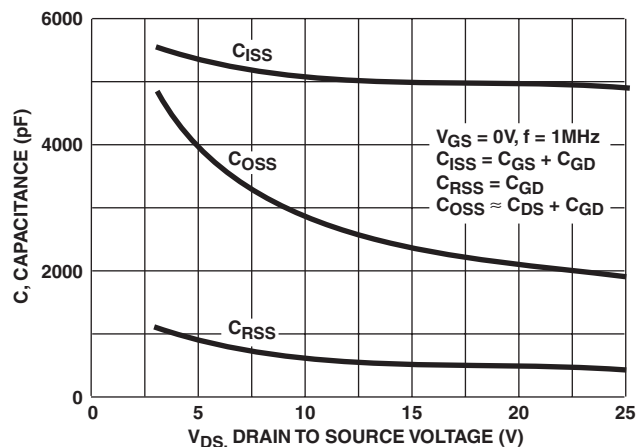
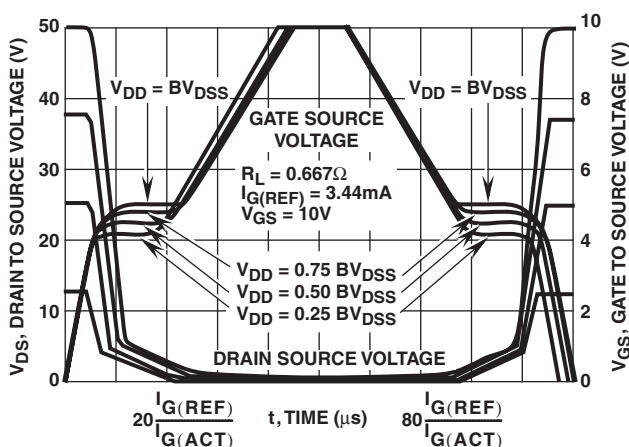


FIGURE 10. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE



NOTE: Refer to Fairchild Application Notes AN7254 and AN7260.

FIGURE 11. NORMALIZED SWITCHING WAVEFORMS FOR CONSTANT GATE CURRENT

Test Circuits and Waveforms

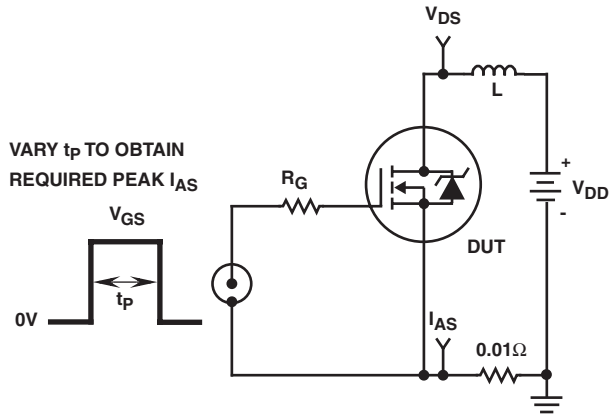


FIGURE 12. UNCLAMPED ENERGY TEST CIRCUIT

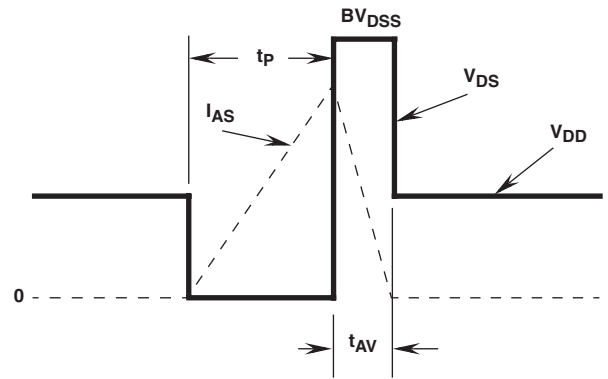


FIGURE 13. UNCLAMPED ENERGY WAVEFORMS

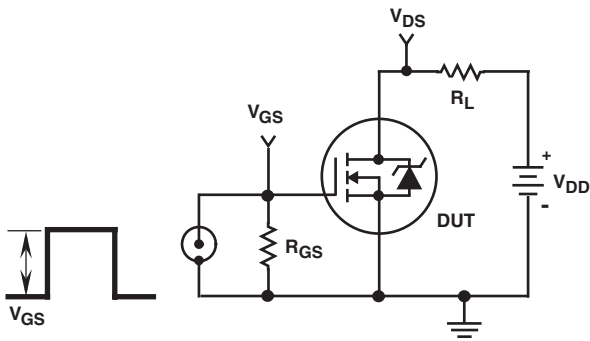


FIGURE 14. SWITCHING TIME TEST CIRCUIT

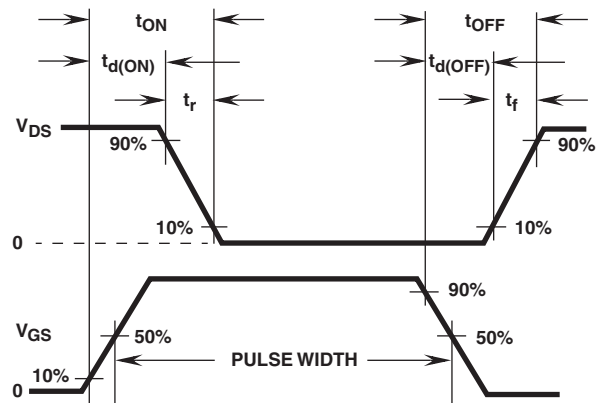


FIGURE 15. RESISTIVE SWITCHING WAVEFORMS

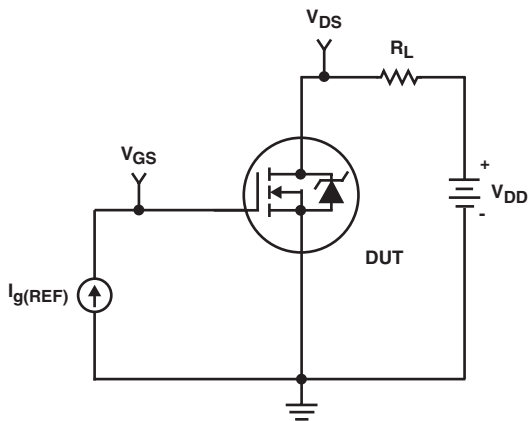


FIGURE 16. GATE CHARGE TEST CIRCUIT

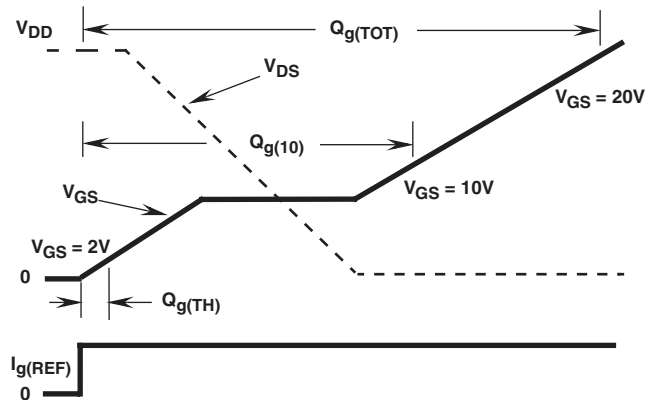


FIGURE 17. GATE CHARGE WAVEFORM

RFG75N05E

PSpice Electrical Model

.SUBCKT RFG75N05 2 1 3 ; rev 10/30/90

*Nominal Temperature = 25°C

CA 12 8 8.98e-9

CB 15 14 8.81e-9

Cin 6 8 4.48e-9

DPLCAP 10 5 DPLCAPMOD

Dbody 7 5 DBODYMOD

Dbreak 5 11 DBREAKMOD

E_{ds} 14 8 5 8 1

E_{gs} 13 8 6 8 1

E_g 6 10 6 8 1

E_{break} 11 7 17 18 58.4

EVTEMP 20 6 18 8 1

IT 8 17 1

L_{drain} 2 5 e-10

L_{gate} 1 9 5e-9

L_{source} 3 7 3e-9

Mos 16 6 8 8 MODMOD

R_{break} 17 18 RBREAKMOD 1

R_{drain} 5 16 R_{SOURCEMOD} 3.07e-3

R_{gate} 9 20 1.2

R_{in} 6 8 1e9

R_{source} 8 7 R_{SOURCEMOD} 2.e-3

RVTEMP 18 19 RVTONEGMOD 1

S1a 6 12 13 8 S1AMOD

S1b 13 12 13 8 S1BMOD

S2A 6 15 14 13 S2AMOD

S2b 13 15 14 13 S2AMOD

V_{bat} 8 19 DC 1

.MODEL S1AMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=-2.48 VOFF=-0.48)

.MODEL S1BMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=0.48 VOFF=-2.48)

.MODEL S2AMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=-2.25 VOFF=2.75)

.MODEL S2ABMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=2.75 VOFF=-2.25)

.MODEL DBODYMOD D (IS=2.23e-12 RS=249e-3 TRS1=2.5e-3 CJO=7.55e-9 TT=4e-8)

.MODEL DBREAKMOD D (RS=8e-2 TRS1=2.5e-3)

.MODEL DPLCAPMOD D (IS=1e-30 N=10 CJO=2.14e-9)

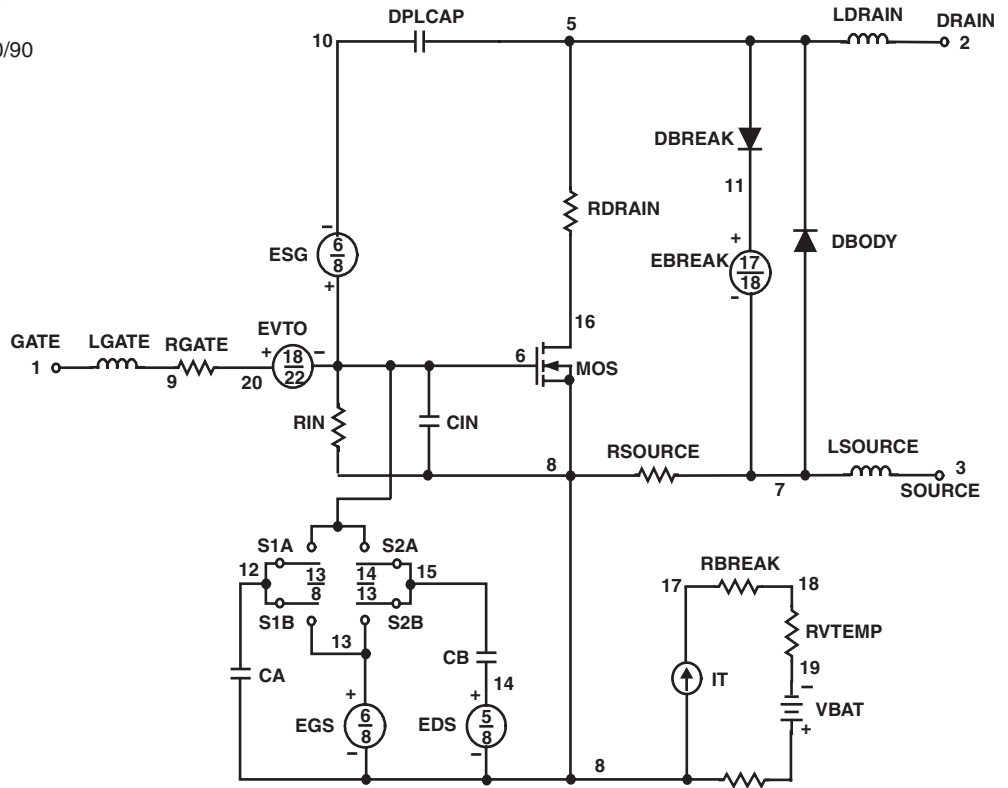
.MODEL RBREAKMOD RES (TC1=9.5e-4 TC2=-1.17e-6)

.MODEL R_{SOURCEMOD} RES (TC1=5.2e-3 TC2=1.37e-5)

.MODEL RVTONEGMOD RES (TC1=-3.78e-3 TC2=-7.51e-7)

.MODEL MODMOD NMOS (VTO=3.48 N=10 IS=1e-30 KP=78.5 TOX=1 L=1u W1u)

.ENDS



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DOMET TM	HiSeC TM	PowerTrench [®]	SuperSOT TM -8	
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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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